

# Multilayer Ferrite Power Beads



## Features

- Monolithic structure for closed magnetic path and high reliability
- Maximum permissible currents up to 6A
- Standard EIA/EIAJ chip sizes such as 0603/1608, 0805/2012, and 1206/3216
- Superior termination bonding strength
- Nickel barrier with solder overplated termination offering excellent solderability and solder leach resistance, suitable for both wave and reflow soldering processes
- RoHS compliant when -T option is specified

## Applications

- Noise suppression in computers and peripherals
- Noise suppression in telecommunications
- Noise suppression in data communications
- Noise suppression in consumer electronics

## Recommended PC Board Land Patterns

CHIP SIZE EIA/EIAJ	L INCH (mm)	G INCH (mm)	H INCH (mm)
0603(1608)	0.102 (2.60)	0.022 (0.55)	0.037 (0.94)
0805(2012)	0.118 (3.00)	0.026 (0.66)	0.057 (1.45)
1206(3216)	0.173 (4.40)	0.059 (1.50)	0.071 (1.80)

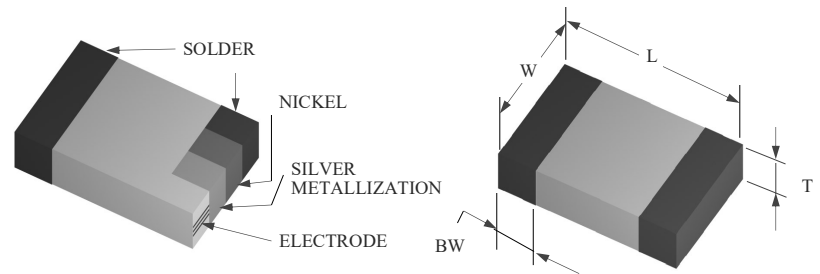
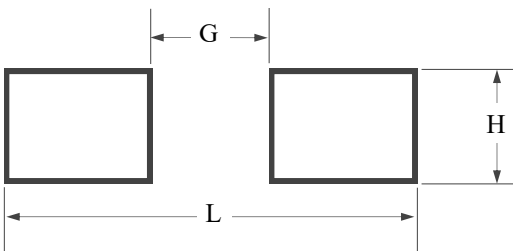
## Operating Temperature

-55°C — +125°C

## Product Identification

MCP 0805 F 600 P T - T  
(1) (2) (3) (4) (5) (6) (7)

- (1) Series code:  
MCP: Multilayer Ferrite Power Bead
- (2) Dimensions: L x W inches  
The first two digits: L (length)  
The last two digits: W (width)
- (3) Characteristic code: F
- (4) Value code: Impedance (ohms at 100 MHz)  
The first two digits are significant. The last digit specifies the number of zeros to follow.
- (5) Tolerance code:  
P = ±25%  
Other tolerances may be available upon request.
- (6) Package code:  
T = Tape & Reel  
B = Bulk
- (7) Termination type code:  
T = 100% Sn plating



CHIP SIZE EIA/EIAJ	LENGTH (L) INCH (mm)	WIDTH (W) INCH (mm)	THICKNESS (T) INCH (mm)	TERMINATION (BW) INCH (mm)
0603/1608	0.063 ± 0.006 (1.60 ± 0.15)	0.031 ± 0.006 (0.80 ± 0.15)	0.031 ± 0.006 (0.80 ± 0.15)	0.014 ± 0.006 (0.36 ± 0.15)
0805/2012	0.079 ± 0.008 (2.00 ± 0.20)	0.049 ± 0.008 (1.25 ± 0.20)	0.035 ± 0.008 (0.90 ± 0.20)	0.020 ± 0.012 (0.51 ± 0.30)
1206/3216	0.126 ± 0.008 (3.20 ± 0.20)	0.063 ± 0.008 (1.60 ± 0.20)	0.043 ± 0.008 (1.10 ± 0.20)	0.020 ± 0.012 (0.51 ± 0.30)

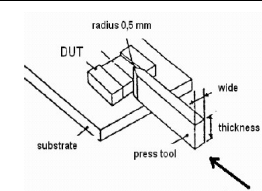
Other sizes and values may be available upon customer's request.

## MCP Series (High Current)

<i>AEM Part Number</i>	<i>Z@100MHz Ω</i>	<i>Tolerance</i>	<i>Max. R<sub>DC</sub> Ω</i>	<i>Max. I A</i>
MCP0603F300PT-T	30	P	0.040	3.0
MCP0603F600PT-T	60	P	0.200	1.0
MCP0603F800PT-T	80	P	0.040	3.0
MCP0603F121PT-T	120	P	0.100	2.0
MCP0603F181PT-T	100	P	0.200	1.0
MCP0603F221PT-T	220	P	0.100	2.0
MCP0603F301PT-T	300	P	0.200	1.0
MCP0603F601PT-T	600	P	0.200	1.0
MCP0603F751PT-T	750	P	0.200	1.0
MCP0805F300PT-T	30	P	0.040	3.0
MCP0805F500PT-T	50	P	0.040	3.0
MCP0805F600PT-T	60	P	0.030	4.0
MCP0805F800PT-T	80	P	0.040	3.0
MCP0805F121PT-T	120	P	0.100	2.0
MCP0805F151PT-T	150	P	0.100	2.0
MCP0805F221PT-T	220	P	0.100	2.0
MCP0805F301PT-T	300	P	0.200	1.0
MCP0805F601PT-T	600	P	0.200	1.0
MCP0805F102PT-T	1000	P	0.200	1.0
MCP1206F190PT-T	19	P	0.030	4.0
MCP1206F300PT-T	30	P	0.040	3.0
MCP1206F500PT-T	50	P	0.040	3.0
MCP1206F800PT-T	80	P	0.040	3.0
MCP1206F101PT-T	100	P	0.050	2.5
MCP1206F121PT-T	120	P	0.100	2.0
MCP1206F301PT-T	300	P	0.200	1.0
MCP1206F601PT-T	600	P	0.100	2.0
MCP1206P310PT-T	31	P	0.010	6.0
MCP1206F900PT-T	60	P	0.100	2.0

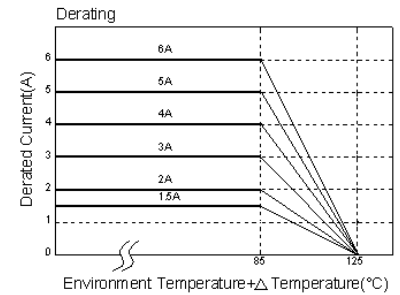
Definition of rated current: When the rated current is applied to a power bead, its temperature rise shall not exceed 20°C. 2

Item	Performance	Test Condition															
Operating Temperature	-55~+125°C (Including self-temperature rise)	--															
Transportation Storage Temperature	-55~+125°C (on board)	For long storage conditions, please see the Application Notice															
Impedance (Z)	Refer to standard electrical characteristics list	Agilent4291 Agilent E4991 Agilent4287 Agilent16192															
DC Resistance		Agilent 4338															
Rated Current		DC Power Supply Over Rated Current requirements, there will be some risk															
Temperature Rise Test	Rated Current < 1A ΔT 20°CMax Rated Current ≥ 1A ΔT 40°CMax	1. Applied the allowed DC current. 2. Temperature measured by digital surface thermometer.															
Life test	Appearance: no damage. Impedance: within±15%of initial value.	Preconditioning: Run through IR reflow for 3 times.( IPC/ JEDEC J-STD-020E Classification Reflow Profiles) Temperature: 125±2°C Applied current: rated current. Duration: 1000±12hrs. Measured at room temperature after placing for 24±2 hrs.															
Load Humidity	RDC : within ±15% of initial value and shall not exceed the specification value	Preconditioning: Run through IR reflow for 3 times.( IPC/ JEDEC J-STD-020E Classification Reflow Profiles) Humidity: 85±2%R.H. Temperature: 85±2°C. Duration:1000hrsMin.Bead:with100%ratedcurrent · Inductance: with 10% rated current Measured at room temperature after placing for 24±2 hrs..															
Thermal shock	Appearance: no damage. Impedance: within±15%of initial value. RDC : within ±15% of initial value and shall not exceed the specification value	Preconditioning: Run through IR reflow for 3 times.( IPC/ JEDEC J-STD-020E Classification Reflow Profiles) Condition for 1 cycle Step1: -55±2°C 30±5 min. Step2: +125±2°C ≅0.5min Step3: +125±2°C 30±5min. Number of cycles: 500 Measured at room temperature after placing for 24±2 hrs.															
Vibration	Appearance : No damage. Impedance : within±15% of initial value RDC : within ±15% of initial value and shall not exceed the specification value	Preconditioning: Run through IR reflow for 3 times.( IPC/ JEDEC J-STD-020E Classification Reflow Profiles) Oscillation Frequency: 10Hz~2KHz~10Hz for 20 minutes Equipment : Vibration checker Total Amplitude:10g Testing Time : 12 hours(20 minutes, 12 cycles each of 3 orientations) °															
Bending	Appearance : No damage. Impedance : within±10% of initial value RDC : within ±15% of initial value and shall not exceed the specification value	Shall be mounted on a FR4 substrate of the following dimensions: >=0805inch(2012mm):40x100x1.2mm <0805inch(2012mm):40x100x0.8mm Bending depth: >=0805inch(2012mm):1.2mm <0805inch(2012mm):0.8mm Duration of 10 sec for a min.															
Shock	Appearance : No damage. Impedance : within±10% of initial value RDC : within ±15% of initial value and shall not exceed the specification value	Test condition: <table border="1"> <thead> <tr> <th>Type</th> <th>Peak Value (g s)</th> <th>Normal duration (D) (ms)</th> <th>Wave form</th> <th>Velocity change (V)ft/sec</th> </tr> </thead> <tbody> <tr> <td>SMD</td> <td>50</td> <td>11</td> <td>Half-sine</td> <td>11.3</td> </tr> <tr> <td>Lead</td> <td>50</td> <td>11</td> <td>Half-sine</td> <td>11.3</td> </tr> </tbody> </table>	Type	Peak Value (g s)	Normal duration (D) (ms)	Wave form	Velocity change (V)ft/sec	SMD	50	11	Half-sine	11.3	Lead	50	11	Half-sine	11.3
Type	Peak Value (g s)	Normal duration (D) (ms)	Wave form	Velocity change (V)ft/sec													
SMD	50	11	Half-sine	11.3													
Lead	50	11	Half-sine	11.3													
Solderability	More than 95% of the terminal electrode should be covered with solder.	a.Method B, 4 hrs @155°C dry heat @235°C±5°C Test time:5 +0/-0.5 seconds. b. Method D category 3. (steam aging 8hours ± 15 min) @ 260°C±5°C Test time: 30 +0/-0.5 seconds..															

Item	Performance	Test Condition						
Resistance to Soldering Heat	Appearance : No damage. Impedance : within±15% of initial value RDC : within ±15% of initial value and shall not exceed the specification value	Number of heat cycles: <table border="1" style="margin-left: 20px;"> <thead> <tr> <th>Temperature (°C)</th> <th>Time (s)</th> <th>Temperature ramp/ immersion and emersion rate</th> </tr> </thead> <tbody> <tr> <td>260 ±5 (solder temp)</td> <td>10 ±1</td> <td>25mm/s ±6 mm/s</td> </tr> </tbody> </table>	Temperature (°C)	Time (s)	Temperature ramp/ immersion and emersion rate	260 ±5 (solder temp)	10 ±1	25mm/s ±6 mm/s
		Temperature (°C)	Time (s)	Temperature ramp/ immersion and emersion rate				
260 ±5 (solder temp)	10 ±1	25mm/s ±6 mm/s						
Depth: completely cover the termination								
Terminal strength	Appearance : No damage. Impedance : within±15% of initial value RDC : within ±15% of initial value and shall not exceed the specification value	 <p>Preconditioning: Run through IR reflow for 3 times. ( IPC/ JEDEC J-STD-020E Classification Reflow Profiles)                      Component mounted on a PCB apply a force &gt;0805inch (2012mm): 1kg                      &lt;=0805inch(2012mm): 0.5kg                      to the side of a device being tested. This force shall be applied for 60 +1 seconds. Also the force shall be applied gradually as not to shock the component being tested.</p>						

### \*\*Derating Curve

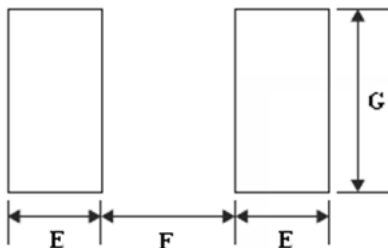
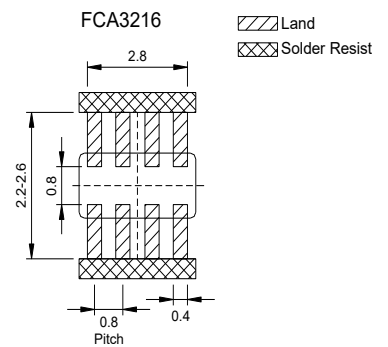
For the ferrite chip bead which withstanding current over 1.5A, as the operating temperature over 85°C, the derating current information is necessary to consider with. For the detail derating of current, please refer to the Derated Current vs. Operating Temperature curve.



## Soldering and Mounting

### Recommended PC Board Pattern

Chip Size						Land Patterns For Reflow Soldering		
Series	Type	A(mm)	B(mm)	C(mm)	D(mm)	E(mm)	F(mm)	G(mm)
MCP	0603	1.6±0.15	0.80±0.15	0.80±0.15	0.30±0.20	0.80	0.85	0.95
	0805	2.0±0.20	1.25±0.20	0.85±0.20	0.50±0.30	1.05	1.00	1.45
		2.0±0.20	1.25±0.20	1.25±0.20	0.50±0.30			
	1206	3.2±0.20	1.60±0.20	1.10±0.20	0.50±0.30	1.05	2.20	1.80



PC board should be designed so that products can prevent damage from mechanical stress when warping the board.

## Soldering

Mildly activated rosin fluxes are preferred. AEM terminations are suitable for re-flow soldering systems. If hand soldering cannot be avoided, the preferred technique is the utilization of hot air soldering tools.

### IR Soldering Reflow:

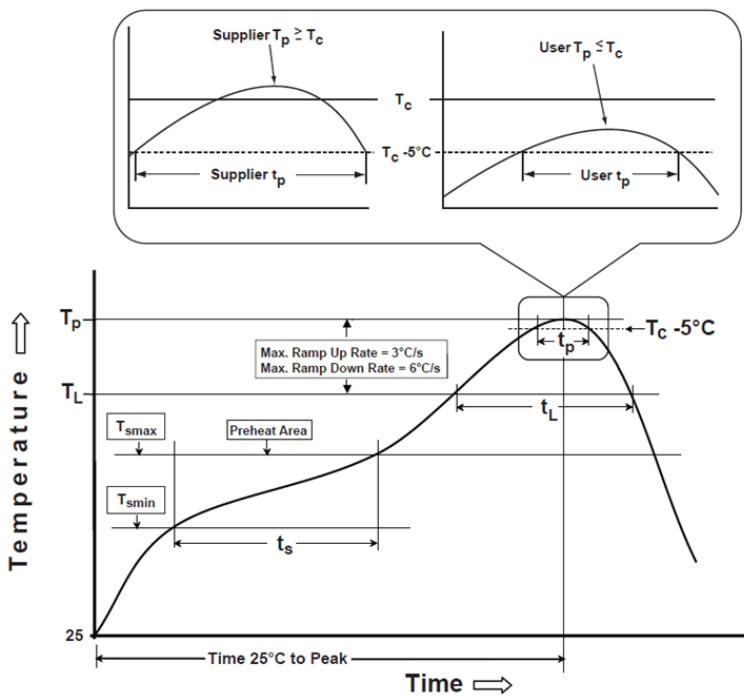
Recommended temperature profiles for lead free re-flow soldering in Figure 1. Table 1.1&1.2 (J-STD-020E)

### Soldering Iron:

Products attachment with a soldering iron is discouraged due to the inherent process control limitations. In the event that a soldering iron must be employed the following precautions are recommended. (Figure 2.)

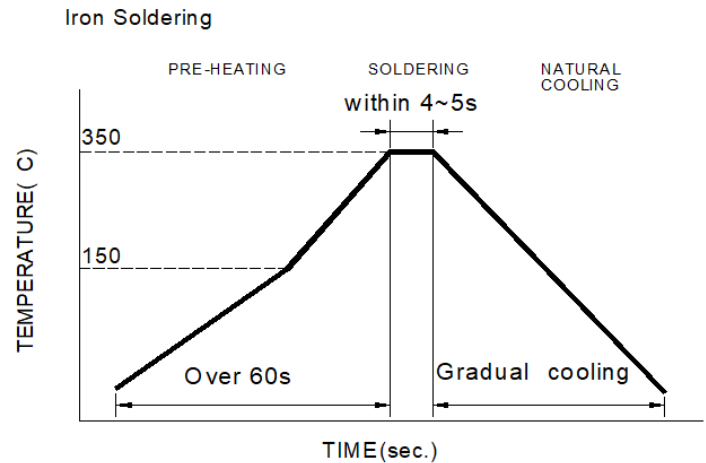
- Preheat circuit and products to 150°C
- Never contact the ceramic with the iron tip • Use a 20 watt soldering iron with tip diameter of 1.0mm
- 350°C tip temperature (max)
- 1.0mm tip diameter (max)
- Limit soldering time to 4~5sec.

Fig.1 IR Soldering Reflow



Reflow times: 3 times max

Fig.2 Iron soldering temperature profiles



Iron Soldering times : 1 times

**T<sub>p</sub>**: maximum peak package body temperature, **T<sub>c</sub>**: the classification temperature. For user (customer) **T<sub>p</sub>** should be equal to or less than **T<sub>c</sub>**.

Table (1.1): Reflow Profiles

Profile Type:	Pb-Free Assembly
Preheat	
-Temperature Min( $T_{smin}$ )	150°C
-Temperature Max( $T_{smax}$ )	200°C
-Time( $t_s$ )from( $T_{smin}$ to $T_{smax}$ )	60-120seconds
Ramp-up rate( $T_L$ to $T_p$ )	3°C/second max.
Liquidus temperature( $T_L$ )	217°C
Time( $t_L$ )maintained above $T_L$	60-150 seconds
Classification temperature( $T_c$ )	See Table (1.2)
Time( $t_p$ ) at $T_c - 5^\circ\text{C}$ ( $T_p$ should be equal to or less than $T_c$ .)	< 30 seconds
Ramp-down rate( $T_p$ to $T_L$ )	6°C /second max.
Time 25°C to peak temperature	8 minutes max.

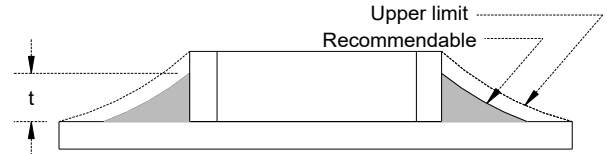
**Table (1.2) Package Thickness/Volume and Classification Temperature (T<sub>c</sub>)**

	Package Thickness	Volume mm <sup>3</sup> <350	Volume mm <sup>3</sup> 350-2000	Volume mm <sup>3</sup> >2000
PB-Free Assembly	<1.6mm	260°C	260°C	260°C
	1.6-2.5mm	260°C	250°C	245°C
	≥2.5mm	250°C	245°C	245°C

Reflow is referred to standard IPC/JEDEC J-STD-020E

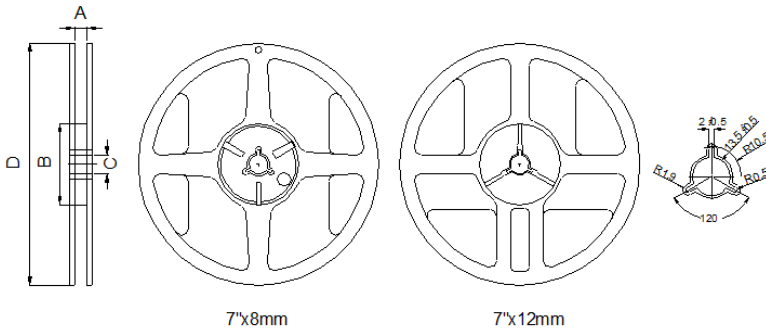
### Solder Volume:

Accordingly increasing the solder volume, the mechanical stress to product is also increased. Exceeding solder volume may cause the failure of mechanical or electrical performance. Solder shall be used not to be exceed as shown in right side:  
 Minimum fillet height = soldering thickness + 25% product height



## Packaging Information

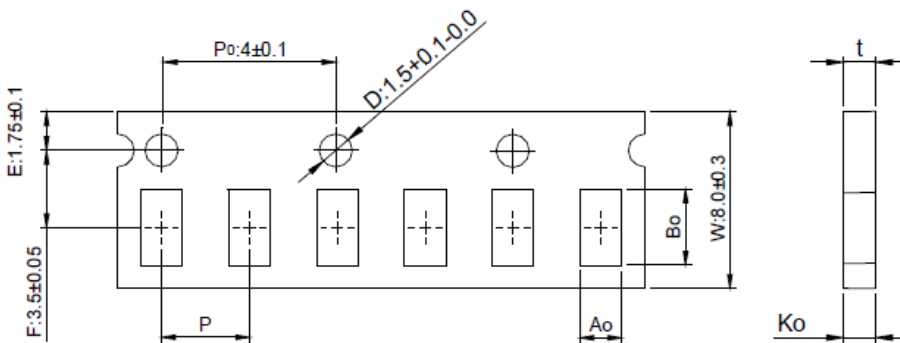
### Reel Dimension



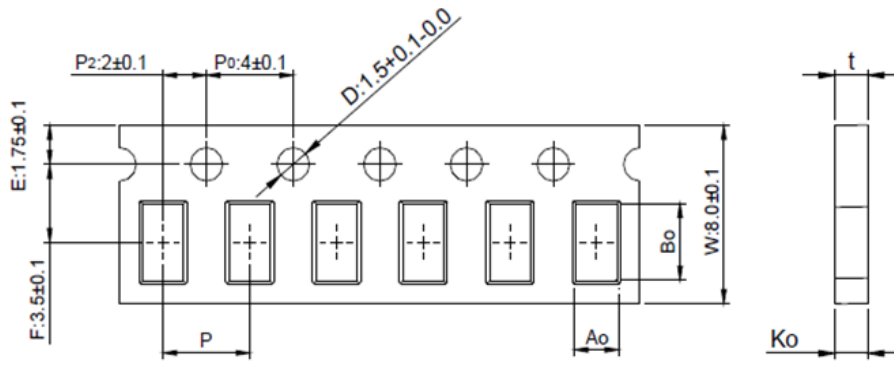
Type	A(mm)	B(mm)	C(mm)	D(mm)
7"x8mm	9.0±0.5	60±2	13.5±0.5	178±2
7"x12mm	13.5±0.5	60±2	13.5±0.5	178±2

### Tape Dimension / 8mm

◆ Material of taping is paper

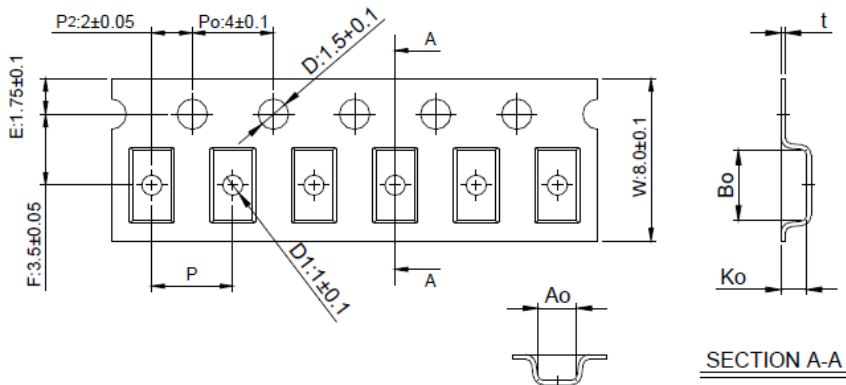


Size	Bo(mm)	Ao(mm)	Ko(mm)	P(mm)	t(mm)
100505	1.12±0.03	0.62±0.03	0.60±0.03	2.0±0.05	0.60±0.03



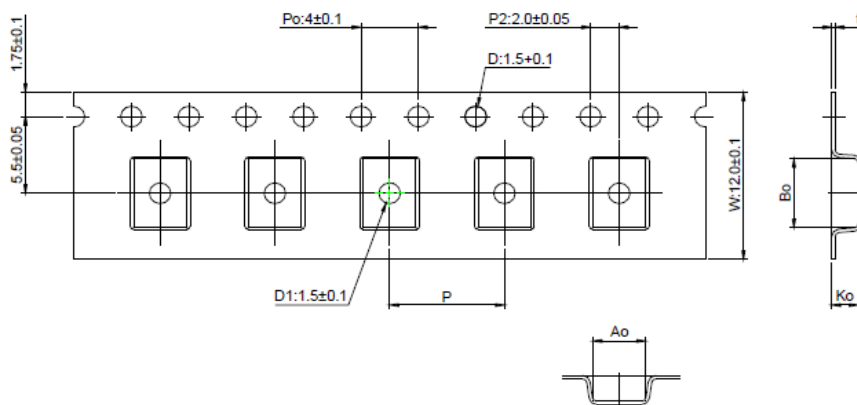
Size	Bo(mm)	Ao(mm)	Ko(mm)	P(mm)	t(mm)
160808	1.80±0.05	0.96+0.05/-0.03	0.95±0.05	4.0±0.10	0.95±0.05
201209	2.10±0.05	1.30±0.05	0.95±0.05	4.0±0.10	0.95±0.05

◆ Material of taping is plastic



Size	Bo(mm)	Ao(mm)	Ko(mm)	P(mm)	t(mm)	D1(mm)
321611	3.35±0.10	1.75±0.10	1.25±0.10	4.0±0.10	0.23±0.05	1.0±0.10

### Tape Dimension / 12mm

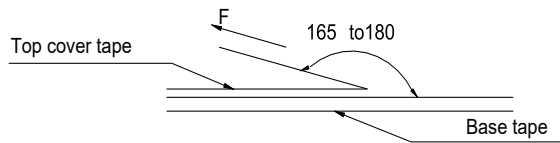


Size	Bo(mm)	Ao(mm)	Ko(mm)	P(mm)	t(mm)	D1(mm)
451616	4.70±0.10	1.75±0.10	1.75±0.10	4.0±0.10	0.24±0.05	1.5±0.10
453215	4.70±0.10	3.45±0.10	1.60±0.10	8.0±0.10	0.24±0.05	1.5±0.10

## Packaging Quantity

Chip Size	453215	451616	321611	201209	160808	100505
Chip / Reel	1000	2000	3000	4000	4000	10000
Inner box	4000	8000	15000	20000	20000	50000
Middle box	20000	40000	75000	100000	100000	250000
Carton	40000	80000	150000	200000	200000	500000

## Tearing Off Force



The force for tearing off cover tape is 15 to 60 grams in the arrow direction under the following conditions.

Room Temp. (°C)	Room Humidity (%)	Room atm (hPa)	Tearing Speed mm/min
5~35	45~85	860~1060	300

### Application Notice

#### ·Storage Conditions(component level)

To maintain the solder ability of terminal electrodes:

1. AEM products meet IPC/JEDEC J-STD-020E standard-MSL, level 1.
2. Temperature and humidity conditions: Less than 40°C and 60% RH.
3. Recommended products should be used within 12 months from the time of delivery.
4. The packaging material should be kept where no chlorine or sulfur exists in the air.

#### ·Transportation

1. Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
2. The use of tweezers or vacuum pick up is strongly recommended for individual components.
3. Bulk handling should ensure that abrasion and mechanical shock are minimized.

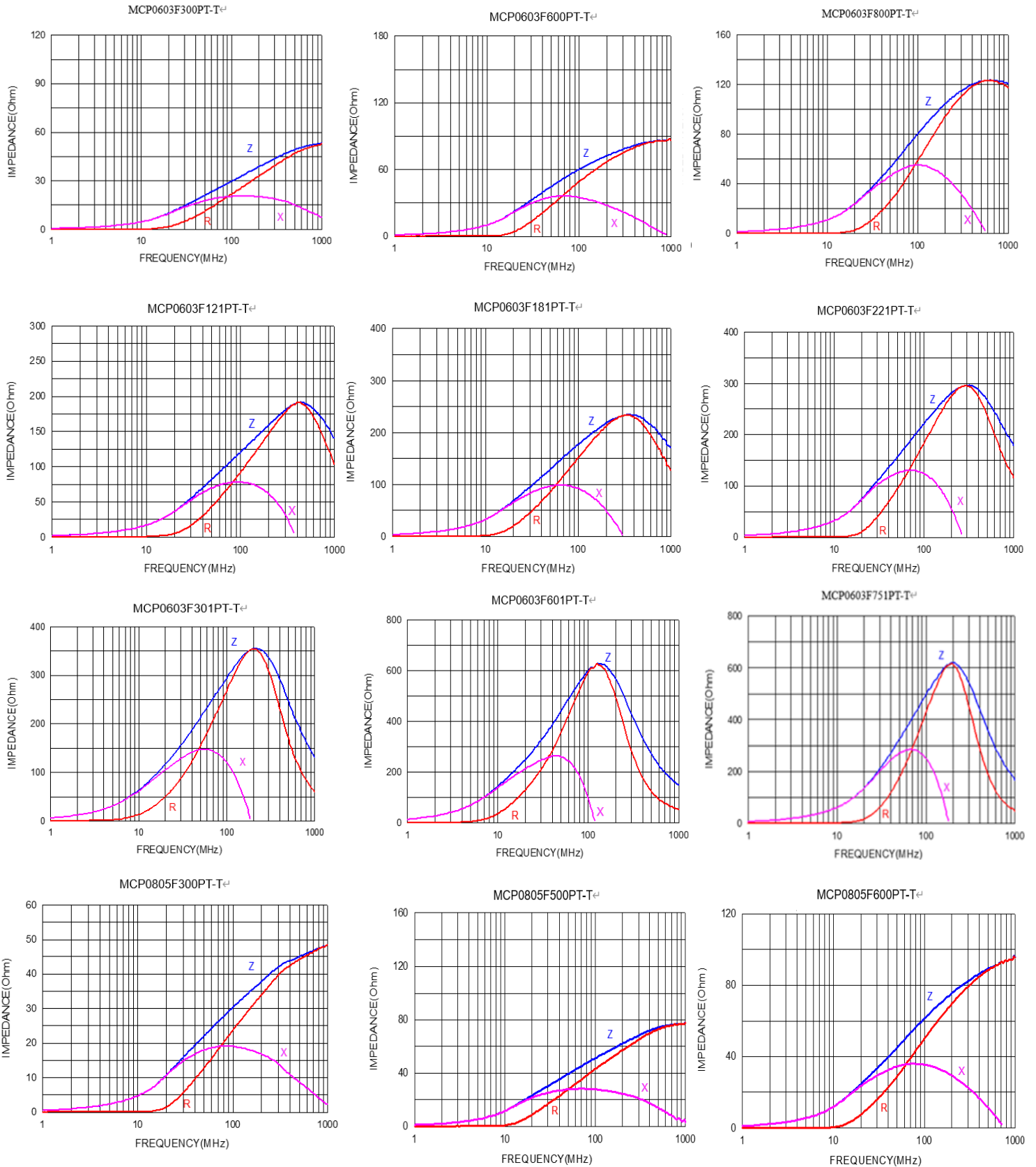
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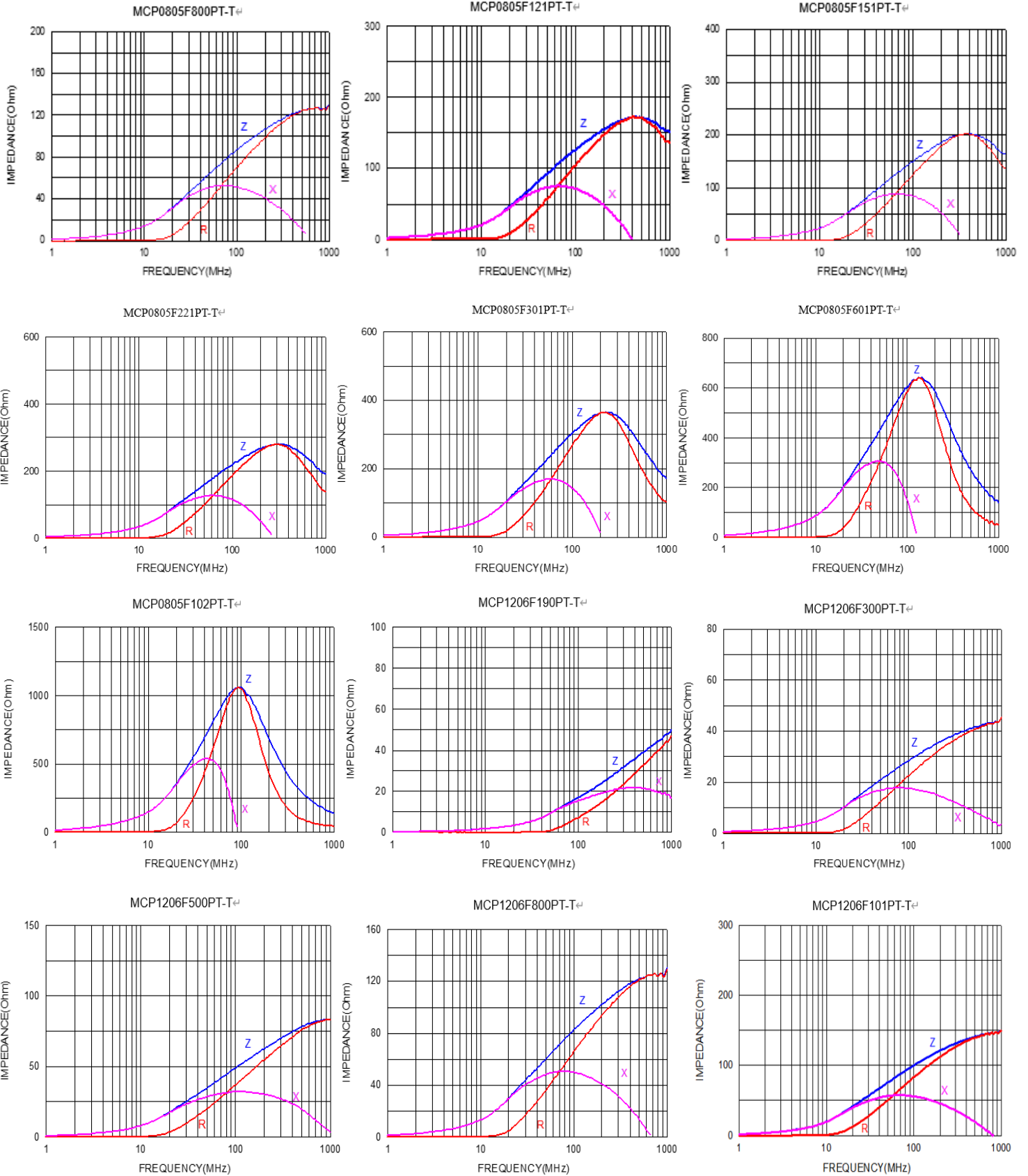
## Electrical Characteristics

(Curves not listed are available upon request)



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